

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---------------------------------|------------------|---------|------------------|
| S1 | 3 | board.ti. and kokufu.in. | US-PGPUB; USPAT; EPO; JPO | OR | ON | 2005/07/08 17:12 |
| S2 | 6 | ("3644166" "4086095" "4967314" "5021296" "5481795" "6488869").PN. | USPAT; EPO; JPO | OR | ON | 2005/07/08 17:14 |
| S3 | 361 | (conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 with (zinc zn nickel ni chromate silane) and (via hole) near2 through and laminat\$3 | USPAT; EPO; JPO | OR | ON | 2005/07/08 18:37 |
| S4 | 135 | "29"/\$ and (conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 with (zinc zn nickel ni chromate silane) and (via hole) near2 through and laminat\$3 | USPAT; EPO; JPO | OR | ON | 2005/07/08 18:44 |
| S5 | 8 | (conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 near3 agent with (zinc zn nickel ni chromate silane) and (via hole) near2 through and laminat\$3 | USPAT; EPO; JPO | OR | ON | 2005/07/08 18:50 |
| S6 | 23 | (copper conduct\$3 metal\$3) near2 (foil layer film) and protect\$3 near3 (material agent) with (zinc zn nickel ni chromate silane) and (via hole) near2 through and circuit near3 board | USPAT; EPO; JPO | OR | ON | 2005/09/12 17:49 |
| S7 | 172 | (wiring circuit\$3 copper conduct\$3 metal\$3) near2 (foil layer film) and (adhesive protect\$3 passivat\$3) near3 (material agent) with (zinc zn nickel ni chromate silane) and (via hole) near4 (substrate board) | USPAT; EPO; JPO | OR | ON | 2005/09/12 17:51 |
| S8 | 91 | (wiring circuit\$3 copper conduct\$3 metal\$3) near2 (foil layer film) and (adhesive protect\$3 passivat\$3) near3 (material agent) with (zinc zn nickel ni chromate silane) and (via hole) near4 (substrate board) and (coat coating dispers\$3) and (pressing laminat\$3) | USPAT; EPO; JPO | OR | ON | 2005/09/12 18:02 |
| S9 | 0 | (wiring circuit\$3 copper conduct\$3 metal\$3) near2 (foil layer film) and (adhesive protect\$3 passivat\$3) near3 (material agent) with (zinc zn nickel ni chromate silane) same (coat coating dispers\$3) and (via hole) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) | USPAT; EPO; JPO | OR | ON | 2005/09/12 18:04 |

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| S10 | 22 | (wiring circuit\$3 copper conduct\$3 metal\$3) near3 (foil layer film) and (adhesive protect\$3 passivat\$3) with (zinc zn nickel ni chromate silane) same (coat coating dispers\$3) and (via hole) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) | USPAT; EPO; JPO | OR | ON | 2005/09/14 15:29 |
| S11 | 25 | (wiring circuit\$3 copper conduct\$3 metal\$3) near3 (foil layer film) with (coat coating dispers\$3) and (adhesive protect\$3 passivat\$3) with (zinc zn nickel ni chromate silane) and (via hole) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) | USPAT; EPO; JPO | OR | ON | 2005/09/12 18:09 |
| S12 | 7 | ("5114543" "5346750" "5725706" "6014929" "6197407" "6359235" "6429114").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/12 18:11 |
| S13 | 109 | ("5346750").URPN. | USPAT | OR | ON | 2005/09/12 18:14 |
| S14 | 9 | ("5780776" "5814883" "5901050" "6015722" "6025648" "6183592" "6222265" "6248959" "6265772").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/12 18:25 |
| S15 | 7 | ("5346750" "5480503" "5481795" "5484647" "5498467" "5576519" "5744758").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/12 18:26 |
| S16 | 7 | ("20010032700" "20030045164" "5346750" "5851646" "6300576" "6523258" "6596406").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/12 18:31 |
| S17 | 5 | ("5346750" "5484647" "5807626" "5888627" "6326694").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/12 18:32 |
| S18 | 1 | "6565954".pn. | USPAT; EPO; JPO | OR | ON | 2005/09/12 18:39 |
| S19 | 1 | "6197407".pn. | USPAT; EPO; JPO | OR | ON | 2005/09/12 18:39 |
| S20 | 19 | (wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3) same (adhesive protect\$3 passivat\$3) with (zinc zn nickel ni chromate silane) and (via hole openning) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) | USPAT; EPO; JPO | OR | ON | 2005/09/14 15:38 |

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| S21 | 34 | (wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3 plating) with (zinc zn nickel ni chromate silane) and (via hole opening) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) and (adhesive protect\$3 passivat\$3) near3 (agent material) | USPAT; EPO; JPO | OR | ON | 2005/09/14 15:39 |
| S22 | 72 | (wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3 plating) with (zinc zn nickel ni chromate silane) and (via hole opening) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) and (adhesive protect\$3 passivat\$3) near3 (agent material layer) | USPAT; EPO; JPO | OR | ON | 2005/09/14 18:28 |
| S23 | 3 | ("4619871" "6107003" "6212769"). PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/14 18:14 |
| S24 | 13 | ("3471631" "4349862" "5292574" "5373110" "5375042" "5590461" "5726863" "5939789" "5977490" "6139777" "6217987" "6259037"). PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/14 18:23 |
| S25 | 148 | (wiring circuit\$3 copper conduct\$3 metal\$3) near4 (foil layer film) with (paint\$3 spray\$3 sputter\$4 deposit\$3 coat coating dispers\$3 plating) with (zinc zn nickel ni chromate silane) and (via hole opening) near4 (substrate board) same (fill\$3 plug\$4) with (conduct\$3 metal\$3) near3 (ink resin paste material) | USPAT; EPO; JPO | OR | ON | 2005/09/14 18:29 |
| S26 | 76 | S25 not S22 | USPAT; EPO; JPO | OR | ON | 2005/09/14 18:30 |